1A SCHOTTKY BARRIER DIODE CHIP SCALE PACKAGE

Product Summary

V_{RRM} (V)	I_O (A)	$V_{F(MAX)}$ (V) @ +25°C	$I_{R(MAX)}$ (mA) @ +25°C
30	1.0	0.40	1.0

Features and Benefits

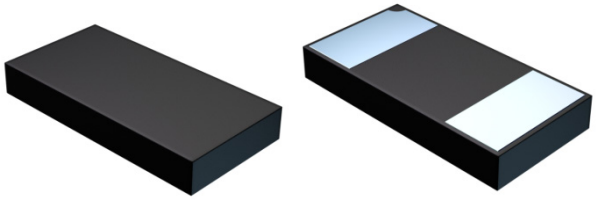
- 2 mm^2 Footprint – 67% smaller than PowerDI123
- Off Board Profile of 0.3mm – 70% thinner than PowerDI123
- Low Forward Voltage Drop reduces Power Dissipation
- Soft switching characteristic ensures that EMI and EFI are minimised
- Guard Ring Die Construction for Transient Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

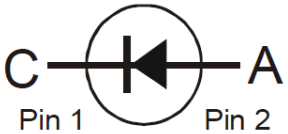
Description and Applications

The SDM1L30CSP is a 30-volt 1A Schottky barrier diode that is optimized for low forward voltage and soft switching characteristics to meet the needs of wireless charging applications. It is housed in a compact chip scale package (CSP) that occupies only 2 mm^2 board-space. It is ideally suited for use in portable applications.

Mechanical Data

- Case: X2-WLB2010-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208 e4
- Polarity: Cathode Dot
- Weight: 0.15mg



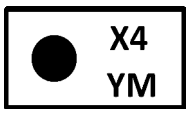


Ordering Information (Note 4)

Part Number	Case	Packaging
SDM1L30CSP-7	X2-WLB2010-2	3,000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



X4 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: B = 2014)
M = Month (ex: 9 = September)
Dot denotes Cathode Pin

Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020
Code	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

© Diodes Incorporated

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Average Rectified Output Current	I_O	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	25	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	130	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	—	0.35	0.40	V	I_F = 1.0A, T_J = +25°C
		—	0.29	—		I_F = 1.0A, T_J = +85°C
Leakage Current (Note 6)	I_R	—	0.47	1.0	mA	V_R = 30V, T_J = +25°C
		—	17	—	mA	V_R = 30V, T_J = +85°C
Total Capacitance	C_T	—	150	—	pF	V_R = 5V, f = 1.0 MHz

Notes: 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout per http://www.diodes.com/datsheets/ap02001.pdf.
6. Short duration pulse test used to minimize self-heating effect.

© Diodes Incorporated

Typical Electrical Characteristics

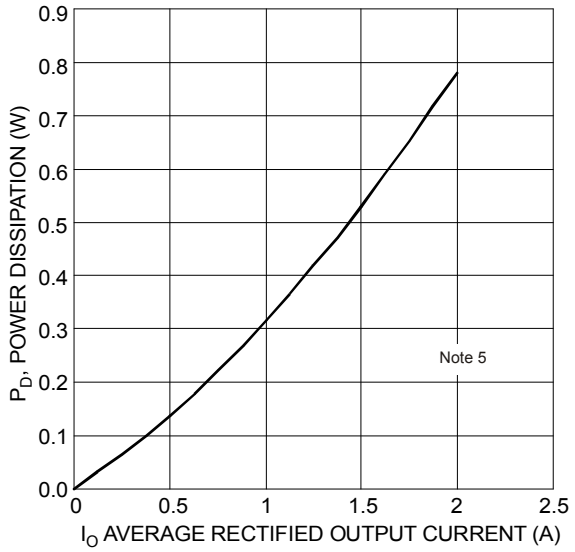


Figure 1 Forward Power Dissipation

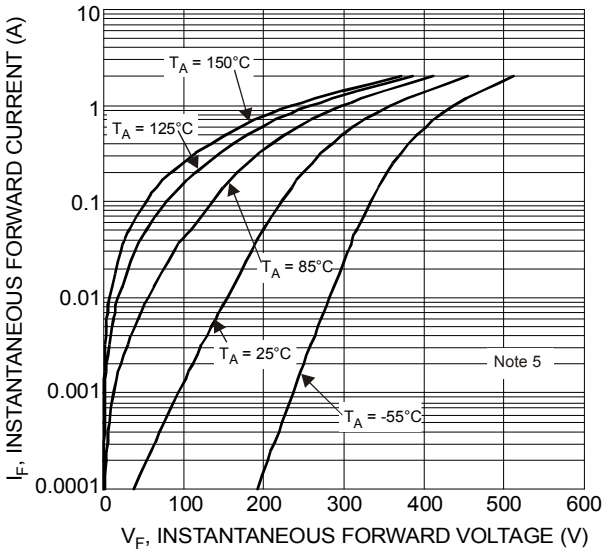


Figure 2 Typical Forward Characteristics

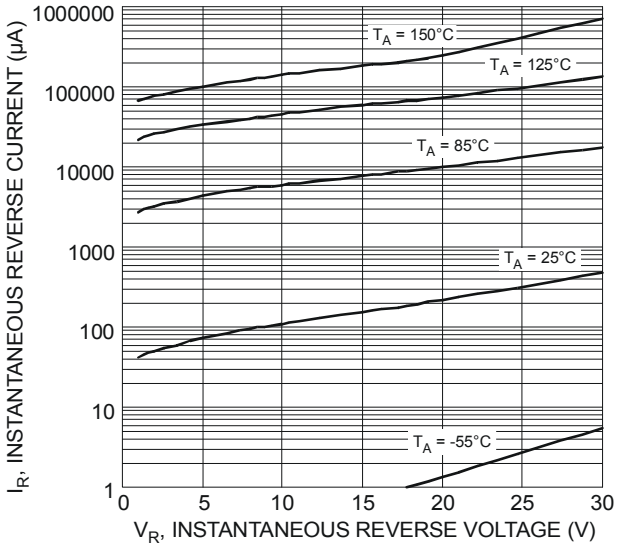


Figure 3 Typical Reverse Characteristics

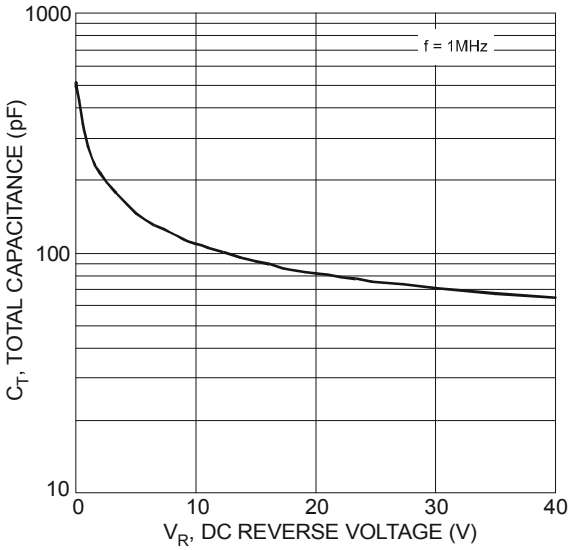


Figure 4 Total Capacitance vs. Reverse Voltage

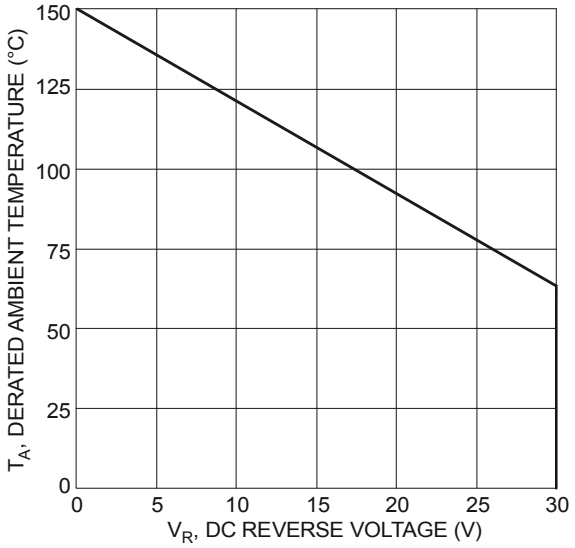
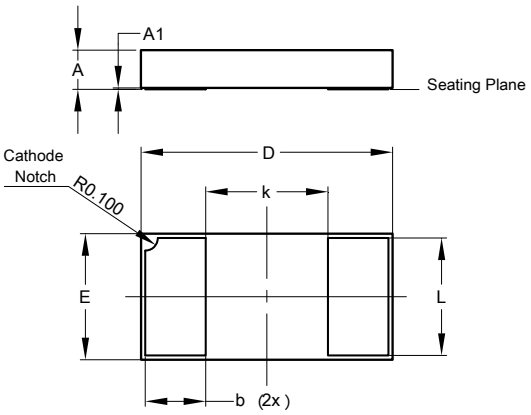


Figure 5 Operating Temperature Derating

© Diodes Incorporated

Package Outline Dimensions

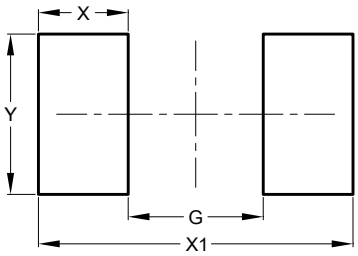
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



X2-WLB2010-2			
Dim	**Min**	**Max**	**Typ**
A	–	0.305	0.290
A1	–	0.02	0.011
b	–	–	0.48
D	1.950	2.050	2.000
E	0.950	1.050	1.000
k	–	–	0.972
L	–	–	0.932
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.872
X	0.580
X1	2.032
Y	1.032

© Diodes Incorporated

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2014, Diodes Incorporated

www.diodes.com